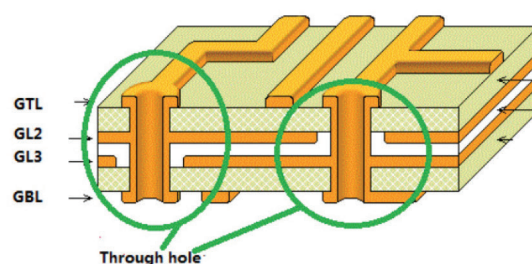
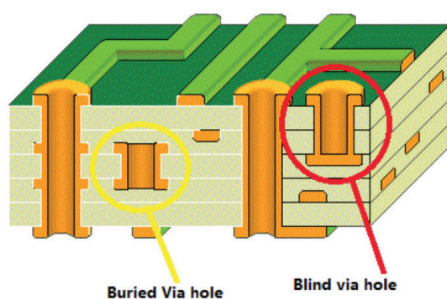


## TECHNOLOGICAL CAPABILITIES OF PCB

DESCRIPTION	CAPABILITY
<b>Board type</b>	SS – Single-sided printed circuit board DS – Double-sided printed circuit board ML – Multilayer printed circuit board up to 12 layers
<b>Basic material</b>	FR4, CEM1, IMS (Al), IMS (Cu) PTFE, RF IZOKART (Pertinaks), VITROPLAST
<b>Manufacturers of basic materials</b>	Kingboard, Nanya, Isola, Rogers, Bergquist etc.
<b>Thermal stability</b>	TG130 – TG210
<b>Thermal conductivity of IMS</b>	0,3 W/m°C 2,0 W/m°C (standard) 5,0 W/m°C
<b>Maximal work panel</b>	500 x 600 mm
<b>Thickness of finished PCB</b>	0,2 mm – 3,2 mm
<b>Thickness of inner layers</b>	0,08 mm – 3,2 mm
<b>Minimum line width</b>	70 μm ( 70 μm )
<b>Thickness of base copper foil</b>	18 μm, 35 μm, 70 μm, 105 μm
<b>Thickness of base copper foil on intermediate layers</b>	18 μm, 35 μm, 70 μm, 105 μm
<b>Diameter of the smallest non-bore hole</b>	0,15 mm
<b>Type of holes</b>	Through hole Blind vias Buried vias Half holes



*Vedno korak naprej.  
Always a step further.*

<b>Blind vias (depth-to-diameter ratio)</b>	1 : 1
<b>Solder mask</b>	Green: matt, glossy (standard) Black White Blue Red Yellow
<b>Minimum gap in fine pitch</b>	70 µm
<b>Silk screen color</b>	White Green Yellow Black Red Blue
<b>Peelable mask</b>	EM55/4748 R-LF (Electra Polymer)
<b>Tented via</b>	With solder mask
<b>Filled via</b>	With non-conductive past, According to IPC-4761 - 6a + 6b + 7
<b>Surface treatment</b>	HAL lead-free (RoHS) Immersion Au (ENIG) Galvanic Au (Hard gold)
<b>Mechanical tolerance</b>	According to DIN ISO 2768 T1
<b>Final product thickness</b>	+/-10 %
<b>Etching tolerance</b>	+/-20 % (+/-10%)

